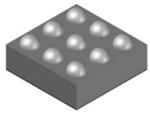


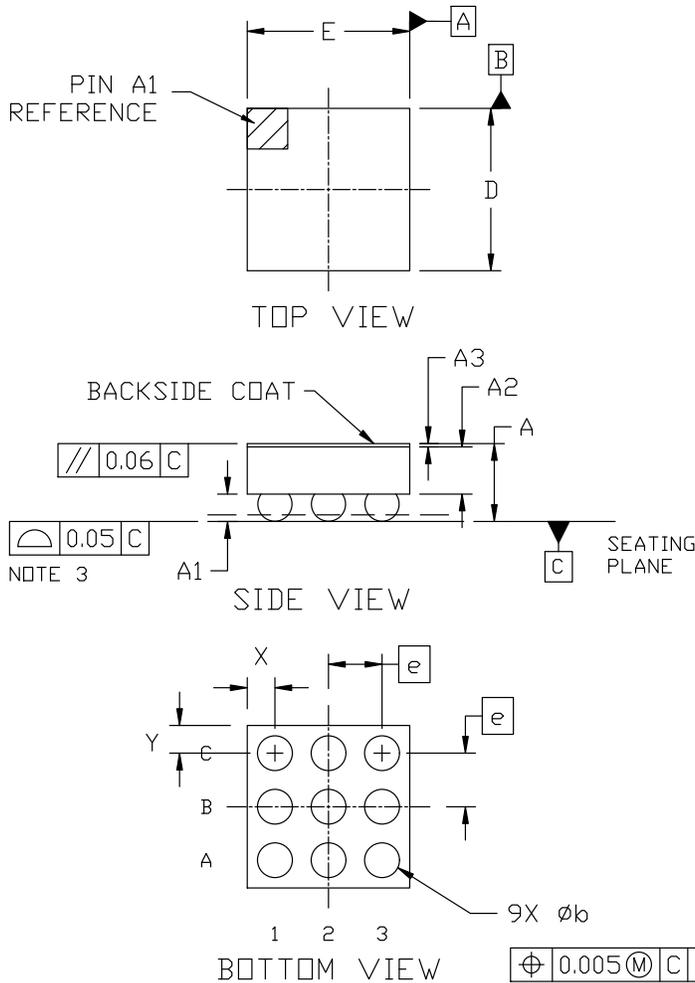
MECHANICAL CASE OUTLINE

PACKAGE DIMENSIONS



WLCSP9 1.215x1.215x0.581
CASE 567QW
ISSUE B

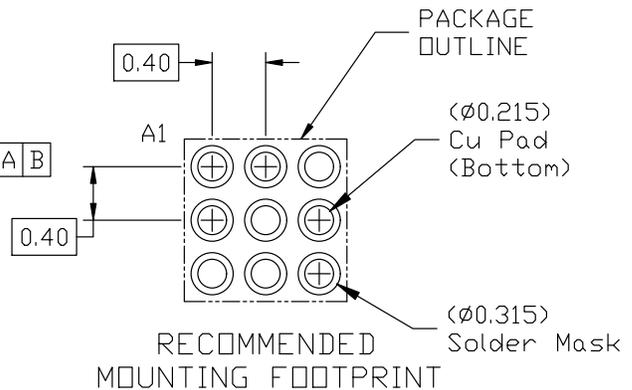
DATE 24 FEB 2023



NOTES:

1. DIMENSIONING AND TOLERANCING PER ASME Y14.5M, 2009.
2. CONTROLLING DIMENSION: MILLIMETERS
3. COPLANARITY APPLIES TO THE SPHERICAL CROWNS OF THE SOLDER BALLS.
4. DATUM C, THE SEATING PLANE, IS DEFINED BY THE SPHERICAL CROWNS OF THE SOLDER BALLS.
5. DIMENSION b IS MEASURED AT THE MAXIMUM SOLDER BALL DIAMETER PARALLEL TO DATUM C.

DIM	MILLIMETERS		
	MIN.	NDM.	MAX.
A	0.542	0.581	0.620
A1	0.183	0.203	0.223
A2	0.335	0.353	0.371
A3	0.022	0.025	0.027
b	0.24	0.26	0.28
D	1.185	1.215	1.245
E	1.185	1.215	1.245
e	0.400 BSC		
X	0.208 REF		
Y	0.208 REF		



* For additional information on our Pb-Free strategy and soldering details, please download the onsemi Soldering and Mounting Techniques Reference Manual, SOLDERM/D.

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DESCRIPTION:	WLCSP9 1.215x1.215x0.581	PAGE 1 OF 1

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